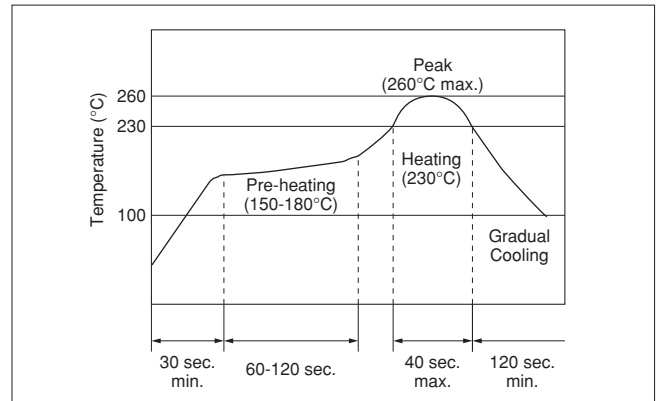


● Soldering and Mounting

1. Standard Reflow Soldering Conditions

(1) Reflow

Filter is soldered twice within the following temperature conditions.



(2) Soldering Iron

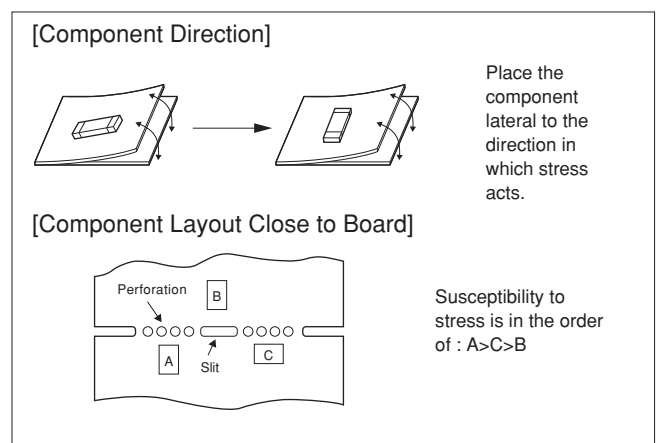
Filter is soldered at $+350\pm 5^{\circ}\text{C}$ for 3.0 ± 0.5 seconds. The soldering iron should not touch the filter while soldering.

(3) Conditions for Placement Machines


The component is recommended for use with placement machines that employ optical placement capabilities. The component might be damaged by excessive mechanical force. Please make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines that utilize mechanical positioning. Please contact Murata for details beforehand.

(4) Other

- The component may be damaged if excess mechanical stress is applied to it mounted on the printed circuit board.
- Design layout of components on the PC board to minimize the stress imposed on the warp or flexure of the board.
- After installing components, if solder is excessively applied to the circuit board, mechanical stress will cause destruction resistance characteristics to degrade. To prevent this, be extremely careful in determining shape and dimension before designing the circuit board diagram.
- When the positioning claws and pick-up nozzle are worn, the load is applied to the components while positioning is concentrated on positioning accuracy, etc. Careful checking and maintenance are necessary to prevent unexpected trouble.
- When correcting components with a soldering iron, the tip of the soldering iron should not directly touch the component. Depending on the soldering conditions, the effective area of terminations may be reduced. Solder containing Ag should be used to prevent electrode erosion.
- Do not use strong acidity flux, more than 0.2wt% chlorine content, in reflow soldering.



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2. Wash

Do not clean or wash the component as it is not hermetically sealed.

3. Coating

In case of overcoating the component, conditions such as material of resin, cure temperature, and so on should be evaluated well.

● Storage and Operating Conditions

1. Product Storage Conditions

Please store the products in a room where the temperature/humidity is stable, and avoid places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to +40°C

Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because solderability may be degraded due to storage under poor conditions.

Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

(1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because quality and solderability may be degraded due to storage in a chemical atmosphere.

(2) Please do not put the products directly on the floor without anything under them to avoid damp places and/or dusty places.

(3) Please do not store the products in places such as a damp heated place or any place exposed to direct sunlight or excessive vibration.

(4) Please use the products immediately after package is opened, because quality and solderability may be degraded due to storage under poor conditions.

(5) To avoid cracking of ceramic element, please do not drop the products.

4. Other

Please be sure to consult with our sales representative or engineer whenever the products are to be used in conditions not listed above.

● Rating

The component may be damaged if excessive mechanical stress is applied.

● Handling

1. Accurate test circuit values are required to measure electrical characteristics. Miscorrelation may be caused if there is any deviation, especially stray capacitance, from the test circuit in the specification.

2. The components, packed in a moisture proof bag (dry pack), are sensitive to moisture. The following treatment is required before applying reflow soldering, to avoid reliability degradation caused by thermal stress. When unpacked, store the component in an atmosphere of reflow 30°C and below 60%R.H., and solder within 1 week.

3. For safety purposes, connect the output of filters to the IF amplifier through a D.C. blocking capacitor. Avoid applying a direct current to the output of ceramic filters.